

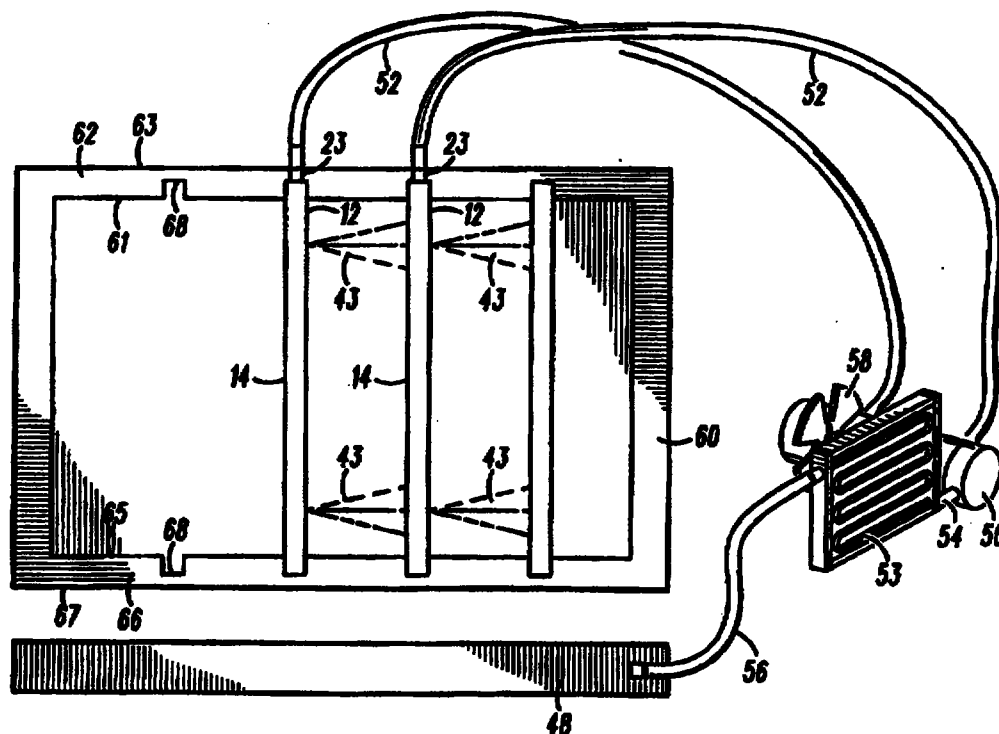
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(54) Title: APPARATUS AND METHOD FOR SPRAY-COOLING AN ELECTRONIC MODULE



(57) Abstract

The apparatus includes a plate (10) having a first layer (12) and a second layer (14) opposed to the first layer (12). The second layer (14) includes a first substrate. A fluid distributing manifold (28) is disposed proximate the first layer (12). A nozzle housing (30) having an aperture (36) is disposed in the first fluid distributing manifold (28).